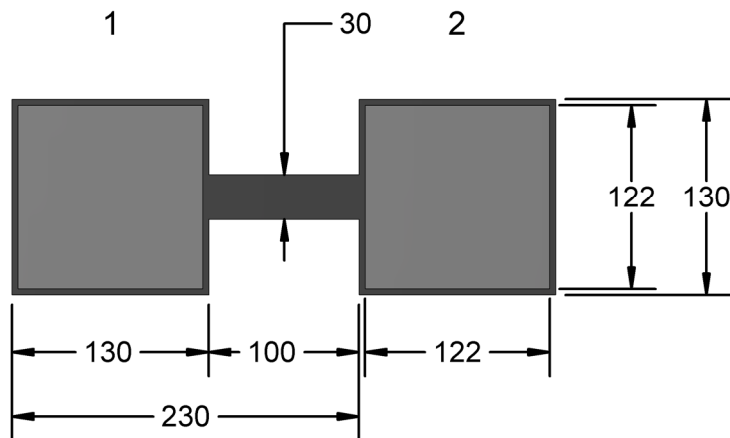


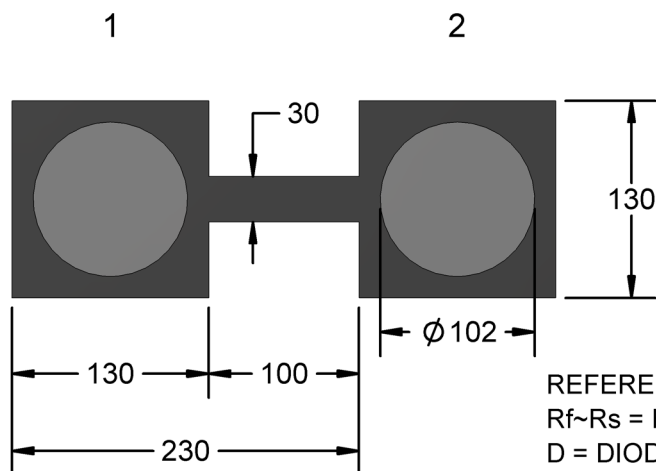
BONDING PAD

DETAIL 1



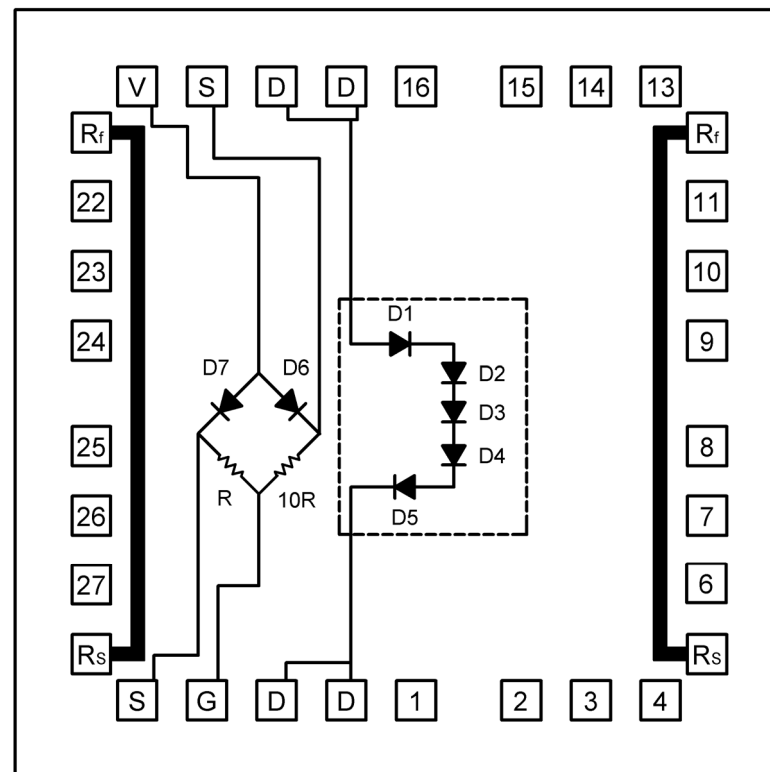
BALL READY

DETAIL 2



REFERENCE:
 Rf-Rs = HEATER Si RESISTIVE
 D = DIODE
 V = +VOLTAGE
 G = GROUND
 S = TEMPERATURE SENSE

PST1 THERMAL DIE 2.5mm x 2.5mm



NOTES:

- 1) DIMENSIONS IN MICRONS (μm) OR AS SPECIFIED.
- 2) THICKNESS: 635 μm (OTHER AVAILABLE).
- 3) PASSIVATION: NITRIDE 10KA THICKNESS (1.0 μm).
- 4) PACKAGING: STANDARD WAFFLE PACK (TRAY).
- 5) PAD METAL THICKNESS: 17KA (1.7 μm).
- 6) SILICON ORIENTATION 1-1-1.
- 7) SILICON TYPE P.

PART NUMBER TABLE

| PART NUMBER | DIE SIZE | DIE PER WAFER | BOND PAD | DETAIL |
|-------------|----------|---------------|--------------------------|--------|
| PST1-B2.5A | 2.5mm | 1600 | 122 μm SQ | 1 |
| PST1-G2.5A | 2.5mm | 1600 | ϕ 102 μm | 2 |

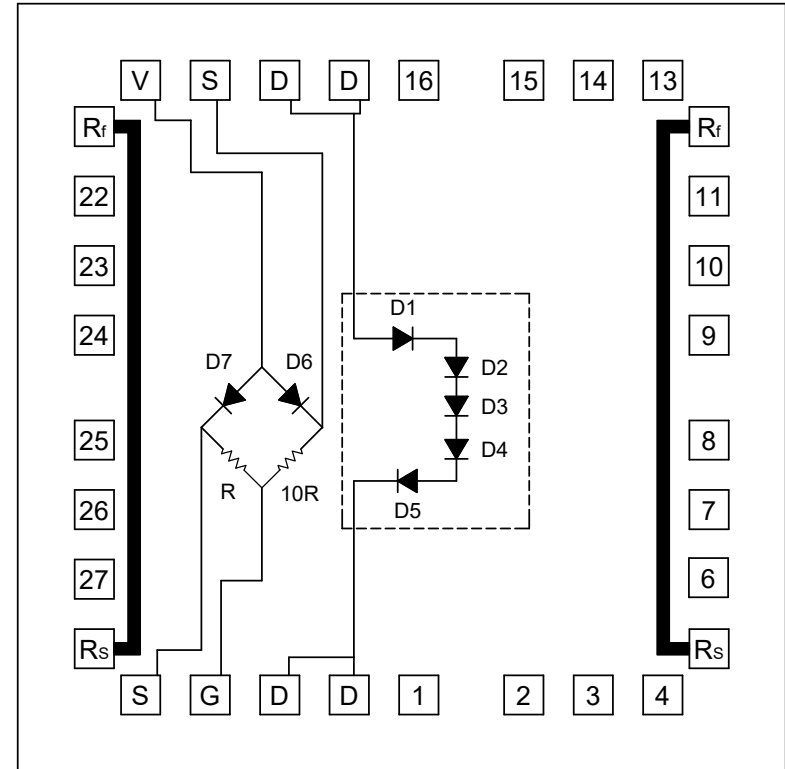
| | | | | | |
|-------------|-----------|---|------|-------------|--------------|
| APPROVALS | DATE | TopLine PST1 THERMAL DIE 2.5mm x 2.5mm | | | |
| DRAWN T. Au | 7/10/2018 | | | | |
| ENG M. Hart | 7/10/2018 | TITLE | | | |
| MFG | | | | | |
| QA | | SCALE | SIZE | DRAWING NO. | REV |
| CUST | | 40:1 | A | 110021 | A |
| REVISED | | DO NOT SCALE DRAWING | | | SHEET 1 OF 4 |

NET LIST

(0,0) is located at the center of the die

| MICRON um | | | |
|-----------|----------|---------|---------|
| PIN# | FUNCTION | X | Y |
| 1 | NC | 56.5 | -1016.5 |
| 2 | NC | 403.5 | -1016.5 |
| 3 | NC | 633.5 | -1016.5 |
| 4 | NC | 863.5 | -1016.5 |
| 5 | Rs (1) | 1016.5 | -863.5 |
| 6 | NC | 1014.5 | -628.5 |
| 7 | NC | 1016.5 | -403.5 |
| 8 | NC | 1016.5 | -173.5 |
| 9 | NC | 1016.5 | 173.5 |
| 10 | NC | 1016.5 | 403.5 |
| 11 | NC | 1016.5 | 633.5 |
| 12 | Rf (1) | 1016.5 | 863.5 |
| 13 | NC | 863.5 | 1016.5 |
| 14 | NC | 633.5 | 1016.5 |
| 15 | NC | 403.5 | 1016.5 |
| 16 | NC | 56.5 | 1016.5 |
| 17 | D (1) | -173.5 | 1016.5 |
| 18 | D (2) | -403.5 | 1016.5 |
| 19 | S (1) | -633.5 | 1016.5 |
| 20 | V | -863.5 | 1016.5 |
| 21 | Rf (2) | -1016.5 | 863.5 |
| 22 | NC | -1016.5 | 633.5 |
| 23 | NC | -1016.5 | 403.5 |
| 24 | NC | -1016.5 | 173.5 |
| 25 | NC | -1016.5 | -173.5 |
| 26 | NC | -1016.5 | -403.5 |
| 27 | NC | -1016.5 | -633.5 |
| 28 | Rs (2) | -1016.5 | -863.5 |
| 29 | S (2) | -863.5 | -1016.5 |
| 30 | G | -633.5 | -1016.5 |
| 31 | D (3) | -403.5 | -1016.5 |
| 32 | D (4) | -173.5 | -1016.5 |

NC = NO CONNECTION



REFERENCE:

Rf-Rs = HEATER Si RESISTIVE ELEMENTS

D = DIODE

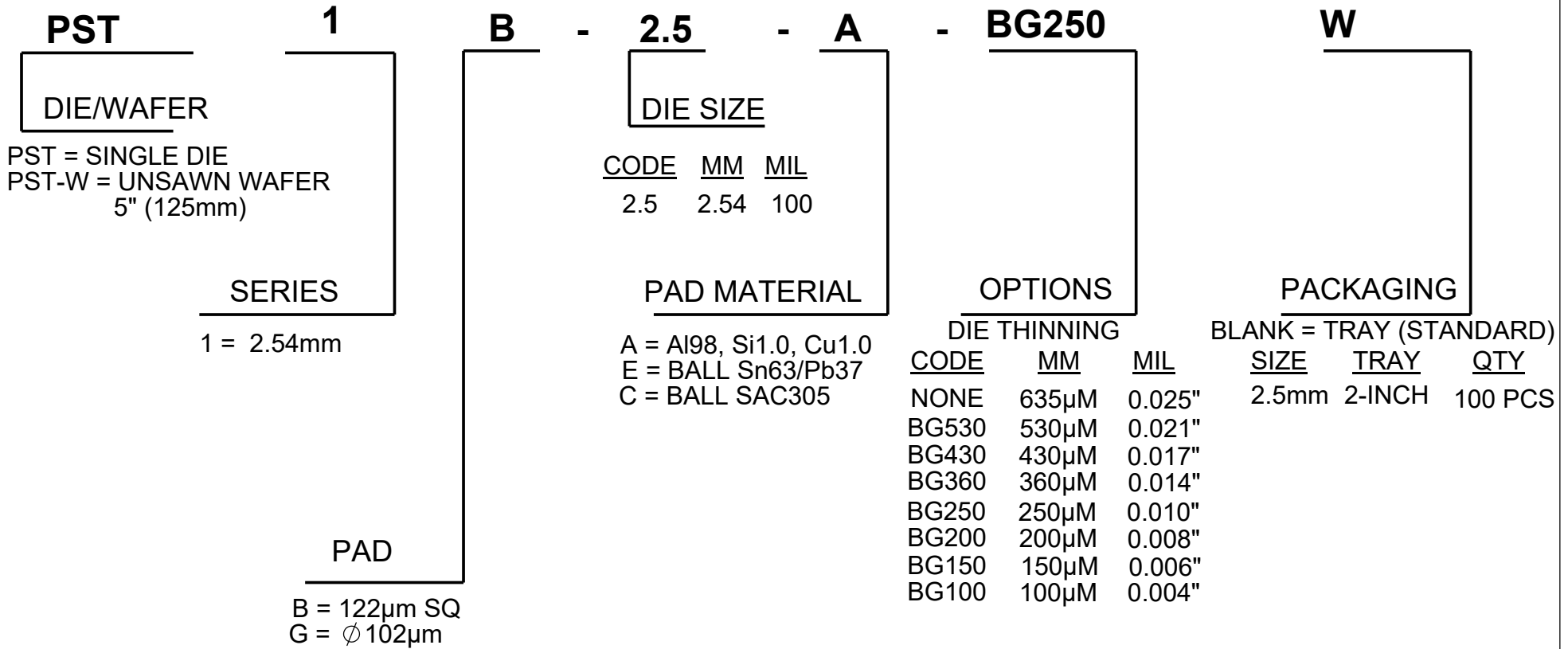
V = +VOLTAGE

G = GROUND

S = TEMPERATURE SENSE

| | | | |
|---|------|-------------|--------------|
| TopLine® | | | |
| TITLE PST1 THERMAL DIE 2.5mm x 2.5mm | | | |
| SCALE | SIZE | DRAWING NO. | REV |
| 40:1 | A | 110021 | A |
| DO NOT SCALE DRAWING | | | SHEET 3 OF 4 |

PART NUMBERING SYSTEM



| | | | |
|--|-----------|-----------------------|--------------|
| TopLine® | | | |
| TITLE PST1 THERMAL DIE 2.5mm x 2.5mm | | | |
| SCALE NONE | SIZE A | DRAWING NO. 110021 | REV A |
| DO NOT SCALE DRAWING | | | SHEET 4 OF 4 |